


- 1 Substrate: 0.0625"±0.007" FR4/G10 or equivalent high temp material. 1/2 oz. Cu clad. SnPb plating
- 2 Pins: Material- Brass Alloy 360 1/2 hard; finish- 10µ" Au over 50µ" Ni (min.).
- 4 Leads: material- BeCu Alloy 194; plating- 60/40 SnPb (150-400µ")

Description: PACKAGE CONVERTOR
 28 position DIP socket to 28 position PLCC SMT foot.

All tolerances: ±0.005" (unless stated otherwise). Materials and specifications are subject to change without notice.

PC-DIP/PLCC28-J-02 Drawing		Status: Released	Scale 3:1	Rev: B
 <p>© 1998 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com</p>	Drawing: P. Reed		Date: 6/19/98	
	File: PC-DIP/PLCC28-J-02 Dwg		Modified: 8/4/98	